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Sheet 1 of 1

INFORMATION DISCLOSURE STATEMENT 	Atty Docket:	00AG11453325
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	Applicant:	MAGNI ET AL.
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	Group:	

U.S. PATENT DOCUMENTS


Examiner Initials		Document Number	Date	Name	Class	Sub Class	Filing Date
<i>AD</i>	AA	5,275,547	01/4/94	Brown	425	129.1	01/3/92
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub Class	Translation
<i>AD</i>	AM	0 813 236	12/17/97	EP	H04L	21188	
<i>AD</i>	AN	87/04973	08/27/87	WO	B00C	45/26	
	AO						
	AP						

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

<i>AD</i>	AQ	Patent abstracts of Japan, Vol. 1998, No. 08 dated June 30, 1998; publication No. 10075040 published on March 17, 1998, entitled "Method for Manufacturing Resin-Coated Circuit Board"; Applicant: Toshiba Chem Corp.
	AR	

EXAMINER: 	DATE CONSIDERED: 2/2004
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.